

2019 全年预期

全球分立体器件(包含功率半导体器件及模组) 唯一保持增长

WSTS Forecast Summary 世界半导体贸易统计(协会)

From the spring 2019 Forecast Meeting, held May 21 to 23, 2019:

Spring 2019	Amounts in US\$M			Year on Year Growth in %		
	2018	2019	2020	2018	2019	2020
Americas	102,997	78,741	84,582	16.4	-23.6	7.4
Europe	42,957	41,609	43,572	12.1	-3.1	4.7
Japan	39,961	36,069	37,473	9.2	- 9.7	3.9
Asia Pacific	282,863	255,666	268,762	13.7	-9.6	5.1
Total World - \$M	468,778	412,086	434,389	13.7	-12.1	5.4
Discrete Semiconductors	24,102	24,450	25,689	11.3	1.4	5.1
Optoelectronics	38,032	37,474	39,699	9.2	-1.5	5.9
Sensors	13,356	13,295	13,892	6.2	-0.5	4.5
Integrated Circuits	393,288	336,867	355,109	14.6	-14.3	5.4
Analog	58,785	55,846	58,639	10.8	-5.0	5.0
Micro	67,233	66,519	69,147	5.2	-1.1	4.0
Logic	109,303	104,912	110,450	6.9	-4.0	5.3
Memory	157,967	109,590	116,873	27.4	-30.6	6.6
Total Products - \$M	468,778	412,086	434,389	13.7	-12.1	5.4

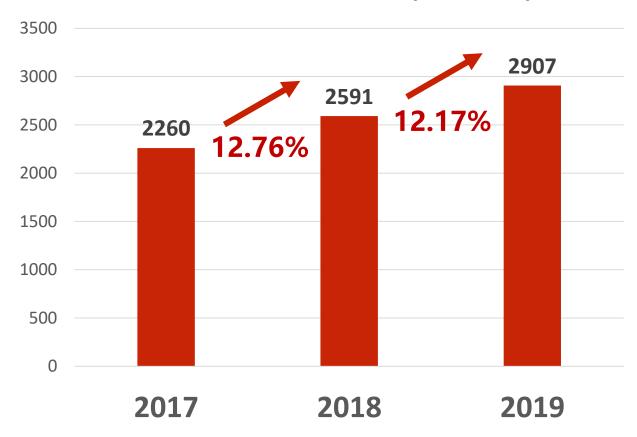
Note: Numbers in the table are rounded to whole millions of dollars, which may cause totals by region and totals by product group to differ slightly.

来源: WSTS

2019 第三季度

国内半导体市场强势回暖 寒冬已过,上下游纷纷满载

中国功率半导体市场规模(亿人民币)



TRENDFORCE 来源: TrendForce

智能家居市场规模



半导体多重赋能



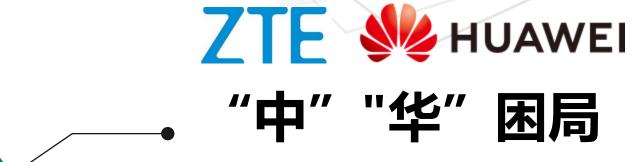
受制于人,如何破局

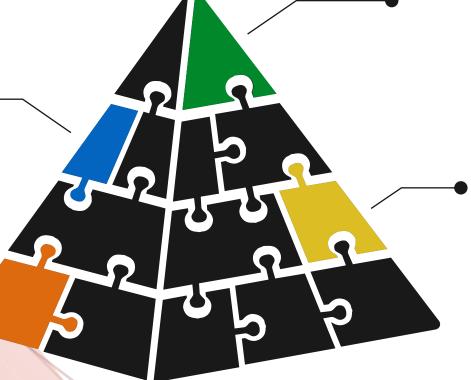


平衡



贸易战局





香港乱局









2012-2017年九国制造强国发展综合指数变动趋势及排名情况



来源:中国工程院,中国制造强国发展指数报告,2018

危机意识 **Crisis Opportunity**

进口替代





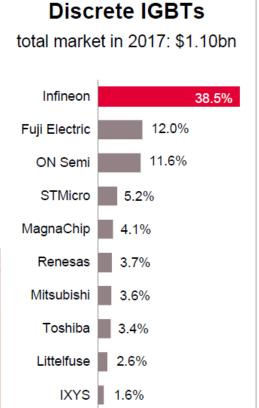


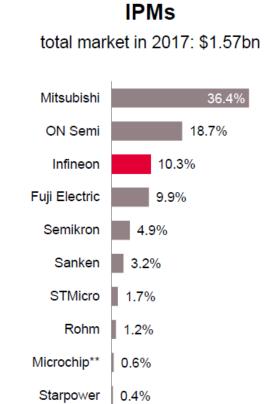




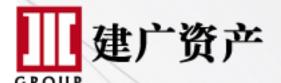


2017功率半导体市占率排行榜





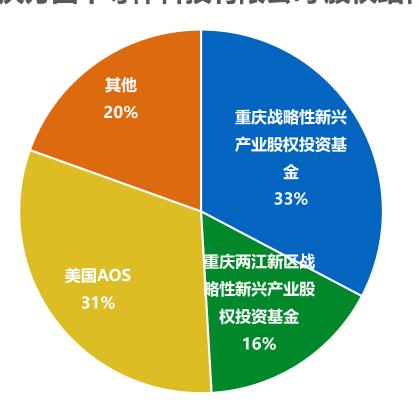
IGBT modules* total market in 2017: \$2.63bn 32.6% Infineon Fuji Electric 10.5% 9.6% Mitsubishi 8.3% Semikron Vincotech Hitachi 3.8% Danfoss 3.2% Toshiba 2.4% 2.0% Bosch Starpower 1.9%







重庆万国半导体科技有限公司 股权结构



新驱动,新市场,新合作

大势所趋

5G

万物智联人工智能工业4.0

企业变革



技术革新





无限商机



新工艺

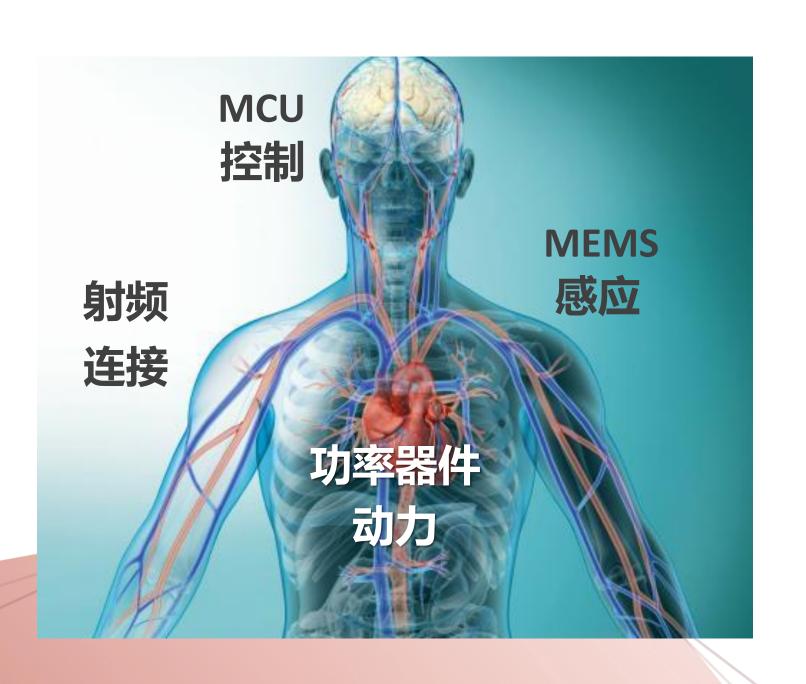


新设备



概念参考: Yole

新驱动,新市场,新合作





新材料, 新挑战, 新机遇

GaN (Gallium Nitride) Si IGBT SiC (Silicon Carbide) Si MOSFET 高功率 1M SiC P_{OUT} (W) **Traction** Si IGBT Inverter Power DC/DC 100k Converter GaN 高频 OBC 10k Aux. DC/DC Converter 1k Si MOSFET GaAs 10k 1M 1k 100k $f_{SW}(Hz)$ 硅基 → 砷化镓 → 碳化硅/氮化镓 来源: 意法微电子 life.augmented

(LDMOS, GaAs更适用于射频)



新材料, 新挑战, 新机遇

烧结银 Ag Sintering



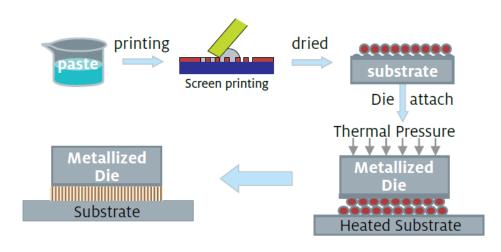
- 更好的电特性
- 更好的散热
- · 更低的CTE 热膨胀系数
 - 更高的可靠性



对比锡膏/锡线/预成型焊片

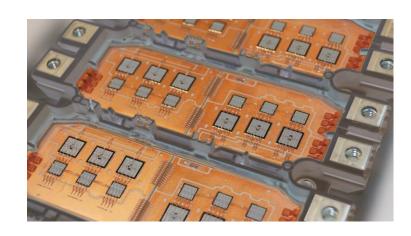
- 更加环保
- 成本偏高
- ・性能优越

Pressure sintering

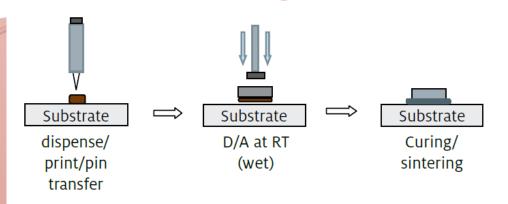


(有压型) 烧结银

- ・高功率模块
- 汽车,工业

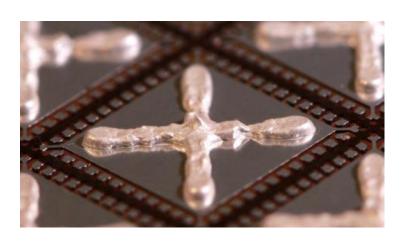


Pressureless sintering

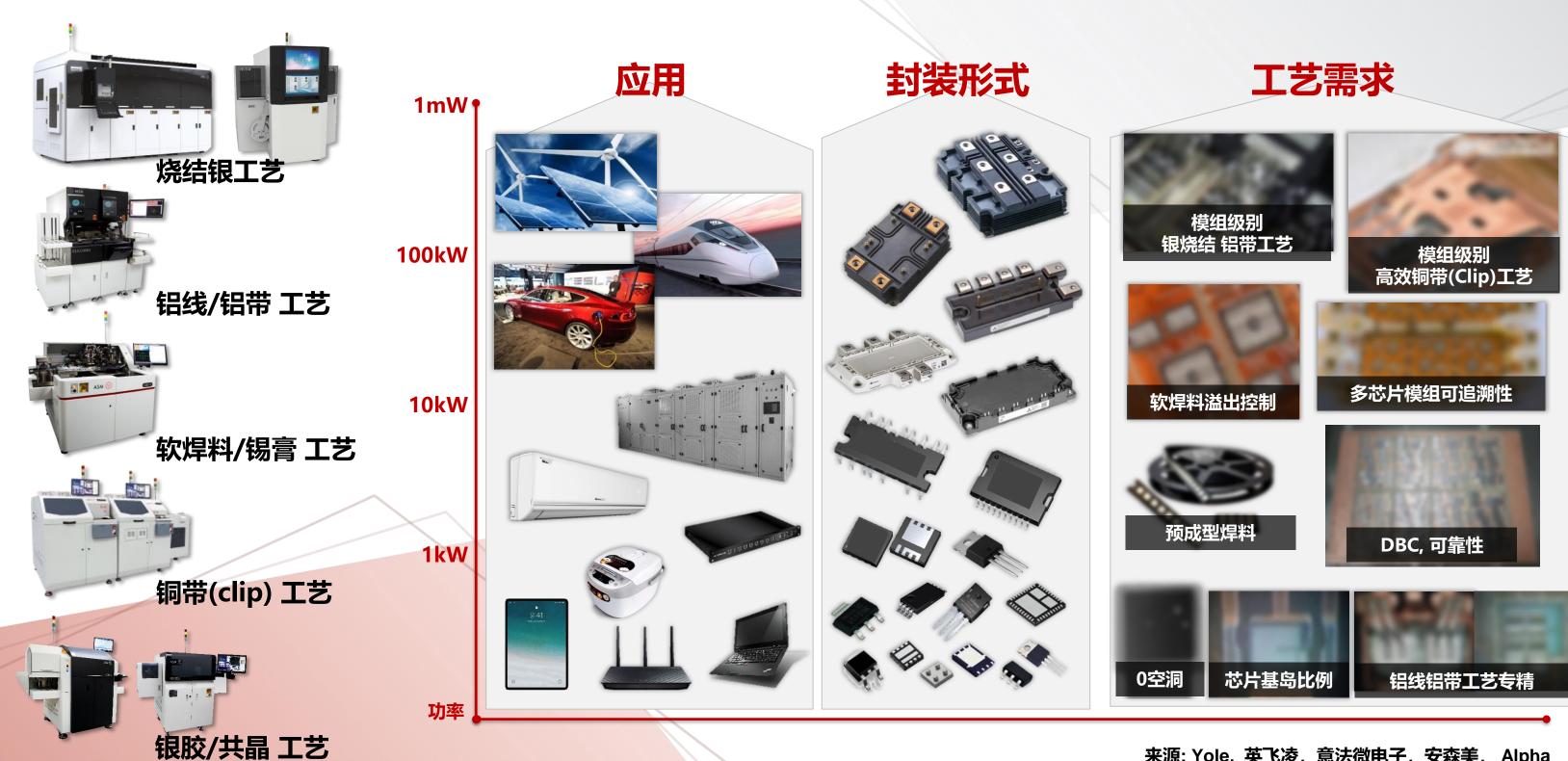


(无压型) 烧结银

- · 5G射频
- · 高功率LED

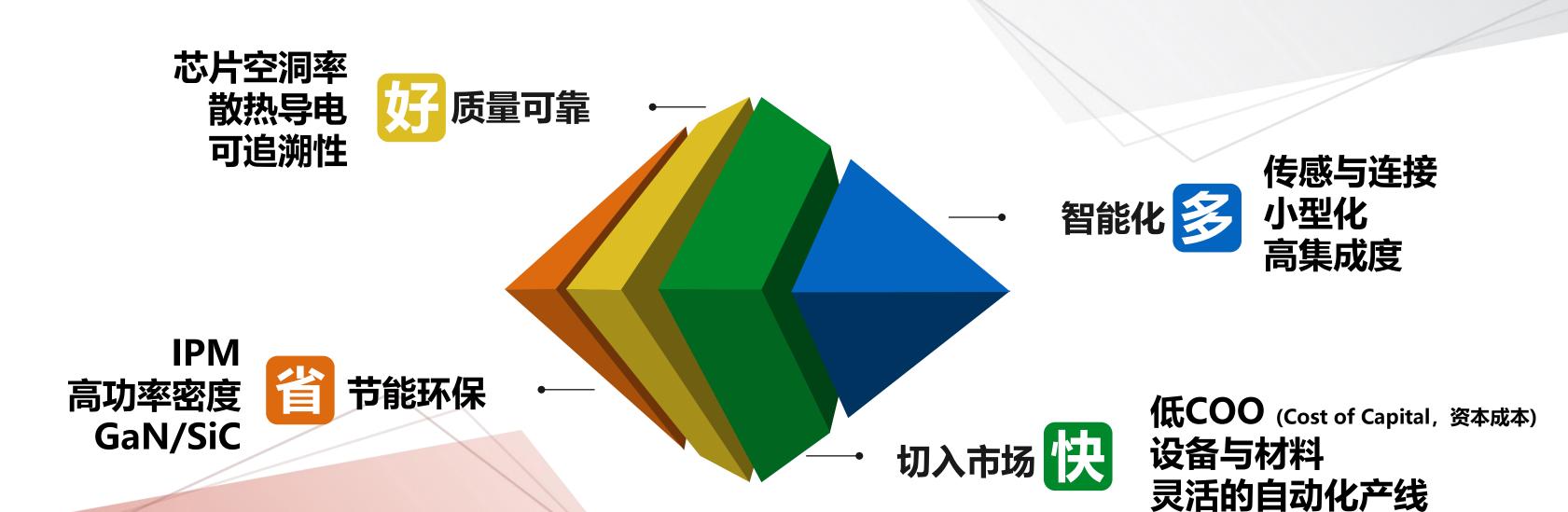


ASMPT功率半导体解决方案 (部分)



来源: Yole, 英飞凌, 意法微电子, 安森美, Alpha

创造产品价值 提升产品附加值



以数据为中心的时代半导体市场蓬勃发展



搜集

镜头模组, 3D 感应, 工业 物联网, 传感, LIDAR



传输

5G, WiFi, LiFi



存储

大数据中心, 云计算



分析

人工智能, TPU, 数据解 析, 高性能计算



可视

AR, VR, Micro LED, Mini LED

CMOS Imaging Sensors

- Active Alignment
- Precision Die Attach
- Silicon Photonics
- RF Filters
- Wire Bonding
- SAW Filters
- BAW Filters
- SMT Solutions
- PVD

- Silicon Photonics
- · TCB
- Wire Bonding
- PLFO
- Laser Dicing

- WLFO
- PLFO
- Pick & Place
- Laser Grooving
- TCB
- PVD/ECD
- Precision Die Attach
- Heterogeneous Integration

- High Precision Die Attach
- Mini/Micro LED **Displays**

ASMPT's 解決方案

ASMPT 全球布局

>2,000

研发团队



>1,400

10

核心前沿技术专利 全球研发中心

智能制造基地



开拓数字化描景

